NS9360 Material Composition

11-Jul-05

Component	Weight	Material		Weight	Content
	[mg]	CAS No.	Name	[mg]	[%]
Chip	15.22	7440-21-3	Silicon	14.90	0.57
		-	PI	0.32	0.01
Substrate	938.44	-	Resin	441.07	16.97
		7440-50-8	Copper	375.40	14.45
		7440-02-0	Nickel	4.70	0.18
		7440-57-5	Gold	0.90	0.04
		-	Brominated Epoxy	93.80	3.61
		-	Other	22.57	0.87
Die attach	1.81	7440-22-4	Silver	1.39	0.05
		-	Epoxy Resin	0.42	0.02
Wire bond	6.36	7440-57-5	Gold	6.36	0.25
Mold Resin	1099.29	7440-21-3	Silica	1000.35	38.50
		-	Epoxy Resin	49.47	1.90
		-	Phenol Resin	49.47	1.90
Solder Ball	537.49	7440-31-5	Tin	518.68	19.96
		7440-22-4	Silver	16.12	0.62
		7440-50-8	Copper	2.69	0.10
Total Weight	2598.61			2598.61	100.00